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April 2015

NDT2955

P-Channel Enhancement Mode Field Effect Transistor

General Description

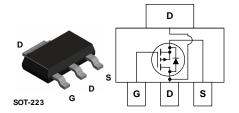
This 60V P-Channel MOSFET is produced using Fairchild Semiconductor's high voltage Trench process. It has been optimized for power management plications.

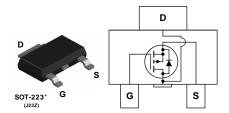
Applications

- DC/DC converter
- Power management

Features

- -2.5 A, -60 V. $R_{DS(ON)}=300m\Omega$ @ $V_{GS}=-10$ V $R_{DS(ON)}=500m\Omega$ @ $V_{GS}=-4.5$ V
- High density cell design for extremely low R_{DS(ON)}
- High power and current handling capability in a widely used surface mount package.





Absolute Maximum Ratings T_A=25°C unless otherwise noted

U					
Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-Source Voltage		-60	V	
V _{GSS}	Gate-Source Voltage		±20	V	
I _D	Drain Current - Continuous	(Note 1a)	-2.5	Α	
	– Pulsed		–15		
P _D	Maximum Power Dissipation	(Note 1a)	3.0	W	
		(Note 1b)	1.3		
		(Note 1c)	1.1		
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	42	°C/W
R _{e,JC}	Thermal Resistance, Junction-to-Case	(Note 1)	12	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
2955	NDT2955	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Avalanc	he Ratings	1		ı		
W _{DSS}	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 30 \text{ V}$, $I_D = 2.5 \text{ A}$			174	mJ
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = -250 \mu\text{A}$	-60			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-60		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$			-10	μΑ
GSSF	Gate-Body Leakage, Forward	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$	-2	-2.6	-4	V
$\Delta V_{GS(th)} \ \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		5.7		mV/°C
R _{DS(on)}	Static Drain-Source	$V_{GS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$		95	300	$m\Omega$
	On–Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -2 \text{ A}$		163 153	500 513	
I _{D(on)}	On–State Drain Current	V_{GS} =-10 V, I_D =-2.5 A, T_J =125°C V_{GS} = -10 V, V_{DS} = -5 V	-12	133	313	Α
9FS	Forward Transconductance	$V_{DS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$	12	5.5		S
	Characteristics	155 10 1, 15 110 11			l	
C _{iss}	Input Capacitance	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V},$		601		pF
Coss	Output Capacitance	f = 1.0 MHz		85		pF
C _{rss}	Reverse Transfer Capacitance	7		35		pF
Switchin	ng Characteristics (Note 2)	1	1	ı	ı	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -30 \text{ V}, I_{D} = -1 \text{ A},$		12	21	ns
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$		10	20	ns
t _{d(off)}	Turn-Off Delay Time			19	34	ns
t _f	Turn-Off Fall Time			6	12	ns
Q_g	Total Gate Charge	$V_{DS} = -30 \text{ V}, I_{D} = -2.5 \text{ A},$		11	15	nC
Q_{gs}	Gate-Source Charge	V _{GS} = -10 V		2.4		nC
Q_{gd}	Gate-Drain Charge			2.7		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
l _s	Maximum Continuous Drain-Source				-2.5	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.5 \text{ A} \text{(Note 2)}$		-0.8	-1.2	V
t _{rr}	Diode Reverse Recovery Time	$I_F = -2.5 \text{ A},$		25		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$		40		nC

Notes

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 42°C/W when mounted on a 1in² pad of 2 oz copper



b) 95°C/W when mounted on a .0066 in² pad of 2 oz



c) 110°C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width < 300μ s, Duty Cycle < 2.0%

Typical Characteristics

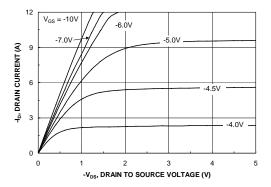


Figure 1. On-Region Characteristics.

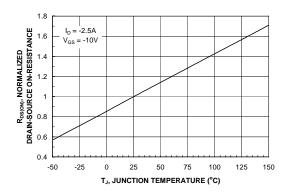


Figure 3. On-Resistance Variation withTemperature.

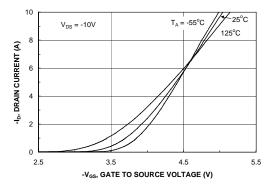


Figure 5. Transfer Characteristics.

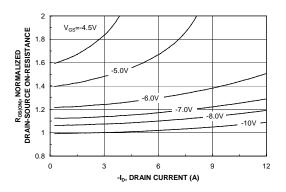


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

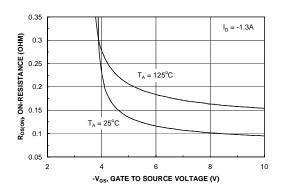


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

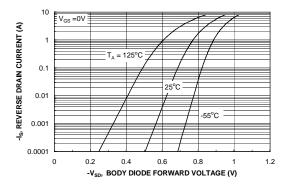
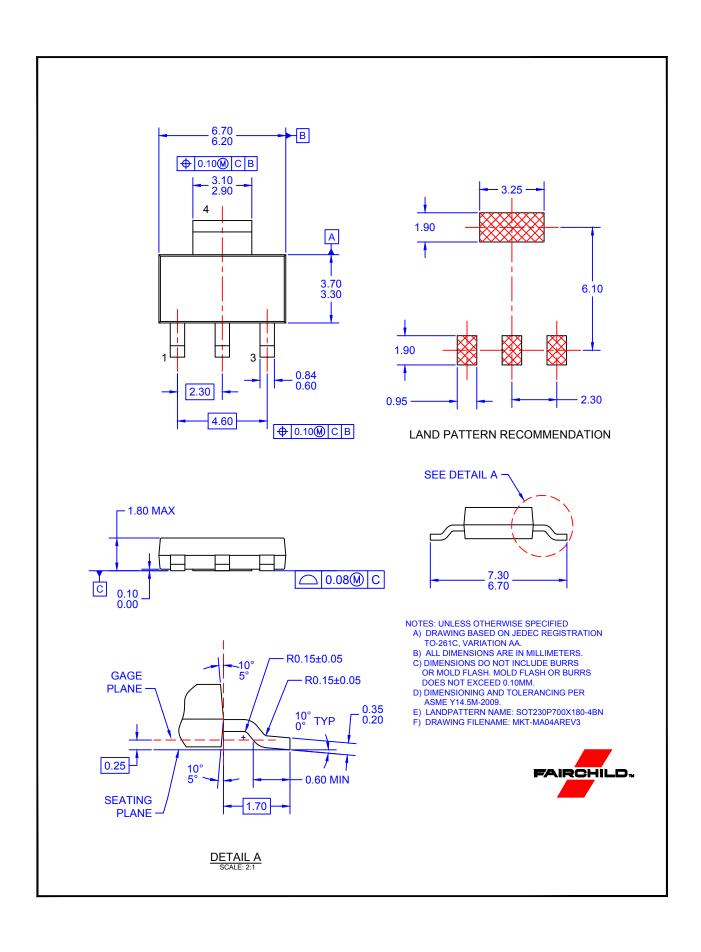


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.



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